

Electronic Acknowledgement Receipt

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Application Number:	10786807
International Application Number:	
Confirmation Number:	3341
Title of Invention:	Method for improving semiconductor wafer test accuracy
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	TRANSMITTAL-085027-0106.pdf	20716 b6d3d8a2c63877b44b40c78bc0f8115068c5	no	1
Warnings:					
Information:					
2		AMENDMENT-085027-0106.pdf	71425 e9d1f7b2d23d4536c70e3842bae22827801f626	yes	9
	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Amendment/Req. Reconsideration-After Non-Final Reject		1	1	
	Claims		2	4	
	Applicant Arguments/Remarks Made in an Amendment		5	9	
Warnings:					
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3	Transmittal Letter	IDS-085027-0106.pdf	22283 1996465226d3d557ca19d985d6212037d853088e0827	no	2
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4	Information Disclosure Statement (IDS) Filed (SB/08)	IDS1449-085027-0106.pdf	86706 c906a7f6d83ab975baed3ec9048c6478d3f86a22c	no	3
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Information:					
6	NPL Documents	2_EDELSTEIN_Advantages_of Copper.pdf	3696109 d4a371204b1d4d03a708a79a6f19d86550008f74	no	9

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7	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a90bcb7a0b154732da48bc4929a0c8baa0b4	no	7
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8	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 7895c75db4d5362c0964035e14853c2a5770e865	no	6
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10	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f00badcc48863ba625de92121b1176ca267a05	no	7
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11	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 813203307462423c3e041a4f39c245e1578ab27	no	8
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33	Fee Worksheet (PTO-875)	fee-info.pdf	31844 a76589c6669936482c3d4c2d4e7a1a7ccf 70ac	no	2

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

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